



## 8-22A-CD-35I

# 8mm Round LED Lamp

## **DESCRIPTIONS**

- The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting
- · Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- · All devices, equipments and machineries must be electrically grounded

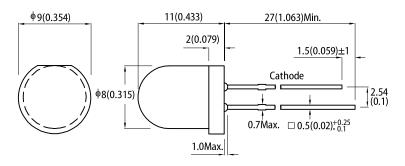
## **FEATURES**

- 8mm diameter big lamp
- · Reliable and rugged
- . Long life solid state reliability
- RoHS compliant

## **APPLICATIONS**

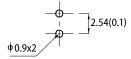
- · Status indicator
- Illuminator
- · Signage applications
- Decorative and entertainment lighting
- · Commercial and residential architectural lighting

## **PACKAGE DIMENSIONS**





### Recommended PCB Layout



- All dimensions are in millimeters (inches).
   Tolerance is ±0.25(0.01") unless otherwise noted.

- 3. Lead spacing is measured where the leads emerge from the package.
  4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice

## **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
9 22A CD 25I	■ Super Bright Red	Red Diffused	280	400	200
8-22A-CD-35I	(GaAlAs)	Red Dillused	*60	*140	30°

- 61/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity / luminous flux: +/-15%.
   \* Luminous intensity value is traceable to CIE127-2007 standards





## ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

# 8-22A-CD-35I

Downston	Symbol	Facilities College	Value		1114
Parameter		Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission I <sub>F</sub> = 20mA	$\lambda_{peak}$	Super Bright Red	655	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Super Bright Red	640	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX $I_F = 20$ mA	Δλ	Super Bright Red	20	-	nm
Capacitance	С	Super Bright Red	45	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Super Bright Red	1.85	2.5	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Super Bright Red	-	10	uA
Temperature Coefficient of $\lambda_{peak}$ I <sub>F</sub> = 20mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambdapeak}$	Super Bright Red	0.13	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ I <sub>F</sub> = 20mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambdadom}$	Super Bright Red	0.06	-	nm/°C
Temperature Coefficient of $V_F$ $I_F = 20\text{mA}$ , $-10^{\circ}\text{C} \le \text{T} \le 85^{\circ}\text{C}$	TC <sub>V</sub>	Super Bright Red	-1.9	-	mV/°C

- The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd:±1nm.)
   Forward voltage: ±0.1V.
   Wavelength value is traceable to CIE127-2007 standards.
   Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

# ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit	
Power Dissipation	P <sub>D</sub>	75	mW	
Reverse Voltage	V <sub>R</sub>	5	V	
Junction Temperature	T <sub>j</sub>	115	°C	
Operating Temperature	T <sub>op</sub>	-40 to +85	°C	
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C	
DC Forward Current	I <sub>F</sub>	30	mA	
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	155	mA	
Electrostatic Discharge Threshold (HBM)	-	3000	V	
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> [2]	-	°C/W	
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> [2]	-	°C/W	
Lead Solder Temperature [3]		260°C For 3 Seconds		
Lead Solder Temperature [4]		260°C For 5 Seconds		

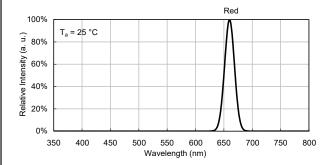
- Notes:
  1. 1/10 Duty Cycle, 0.1ms Pulse Width.
  2.  $R_{th,ls}$ ,  $R_{th,ls}$  Results from mounting on PC board FR4 (pad size  $\geq$  16 mm² per pad).
  3. 2mm below package base.
  4. 5mm below package base.
  Contains the moistained between 40% and 60% in production area are recomm
- 5. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



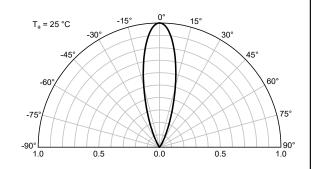


### 8-22A-CD-35I **TECHNICAL DATA**

### **RELATIVE INTENSITY vs. WAVELENGTH**

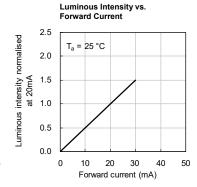


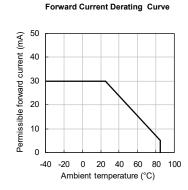
### **SPATIAL DISTRIBUTION**

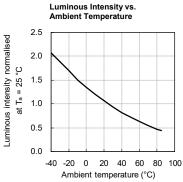


## **SUPER BRIGHT RED**

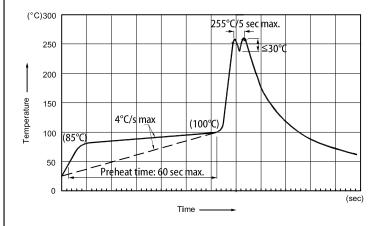
Forward Current vs. Forward Voltage 50 T<sub>a</sub> = 25 °C 40 Forward current (mA) 30 20 10 1.5 1.7 1.9 2.1 2.3 Forward voltage (V)







## **RECOMMENDED WAVE SOLDERING PROFILE**



- Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260  $^{\circ}\mathrm{C}$
- 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sec (5 sec max).
- 3. Do not apply stress to the epoxy resin while the temperature is above 85°C.
  4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5. SAC 305 solder alloy is recommended.6. No more than one wave soldering pass.